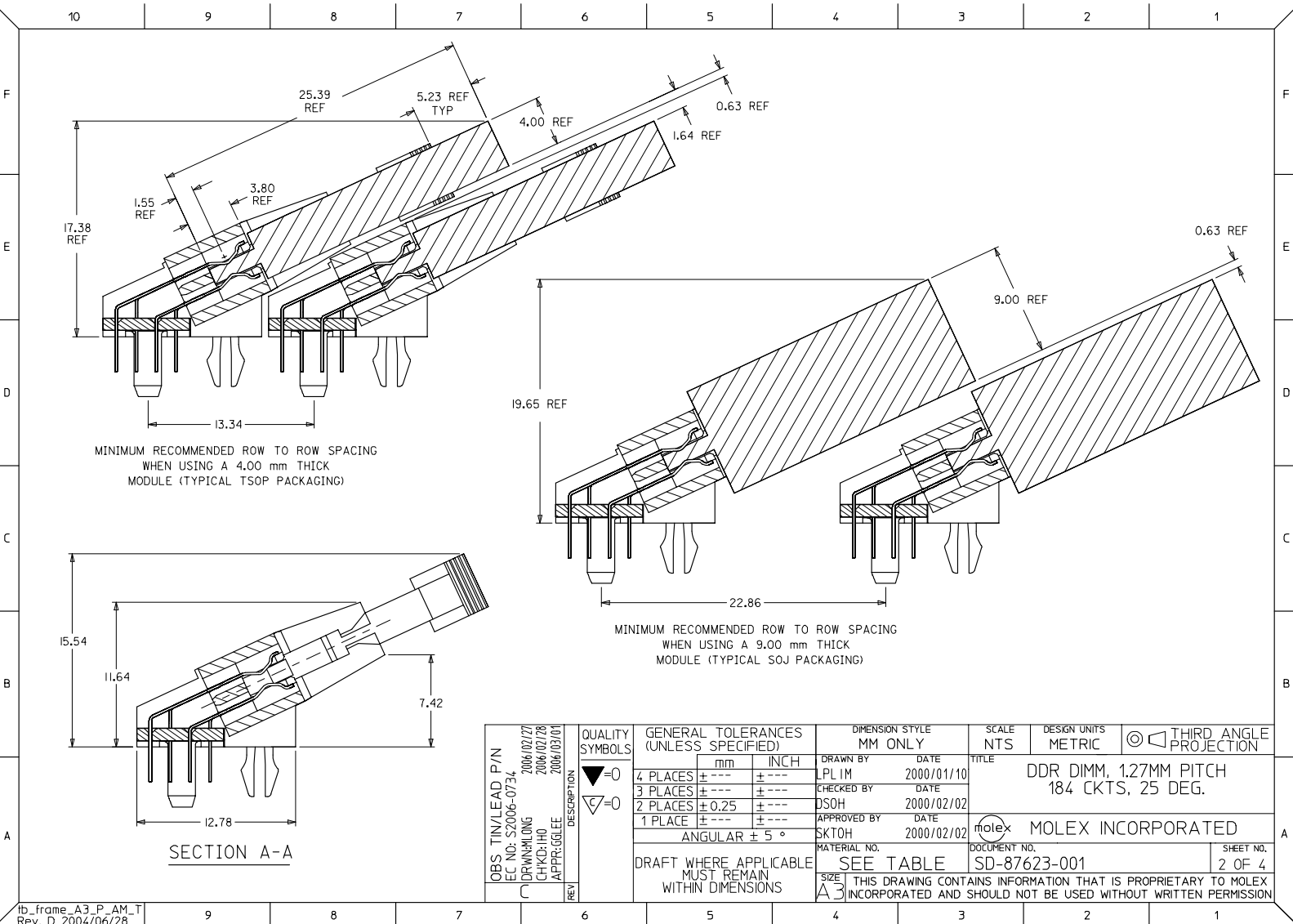


- NOTES:**
- MATERIALS:** HOUSING & BASEPLATE - LCP, GLASS FILLED, UL 94V-0, COLOR: BLACK  
LATCH - HIGH TEMP NYLON, GLASS FILLED, UL 94V-0, COLOR: BEIGE  
TERMINAL AND FORKLOCK - COPPER ALLOY
  - FINISHES:** CONTACT AREA: SEE TABLE ON SHEET 4  
SOLDER TAILS: 2.54µm/100µ" MIN. TIN  
OVER 1.27mm/50µ" MIN. NICKEL
  - PRODUCT SPECIFICATIONS:** PS-87623-002 FOR PERFORMANCE SPECIFICATIONS.
  - DATE CODE** SHALL BE MARKED LEGIBLY AS SHOWN: XX XX  
YEAR WEEK
  - PART NUMBER** SHALL BE MARKED LEGIBLY AS SHOWN: 87623-0XXX  
REFER TO TABLE

OBS TIN/LEAD P/N EC NO. S2006-0734 2006/02/27 DRAWING LONG CHKD: HHO 2006/02/28 APPR: GLEE 2006/03/01	QUALITY SYMBOLS ▽=0 ▽=0	GENERAL TOLERANCES (UNLESS SPECIFIED)	DIMENSION STYLE		SCALE	DESIGN UNITS	THIRD ANGLE PROJECTION
			MM ONLY	NTS	METRIC		
			mm	INCH	TITLE		
		4 PLACES ± --- ± ---	DRAWN BY LPLIM		DATE 2000/01/10		
		3 PLACES ± --- ± ---	CHECKED BY		DATE 2000/02/02		
		2 PLACES ± 0.25 ± ---	APPROVED BY		DATE 2000/02/02		
		1 PLACE ± --- ± ---	SKTOH		DATE 2000/02/02		
		ANGULAR ± 5 °	MATERIAL NO.		DOCUMENT NO.		
			SEE TABLE		SD-87623-001		
			SIZE A3		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION		
		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS			MOLEX INCORPORATED		
					SHEET NO. 1 OF 4		

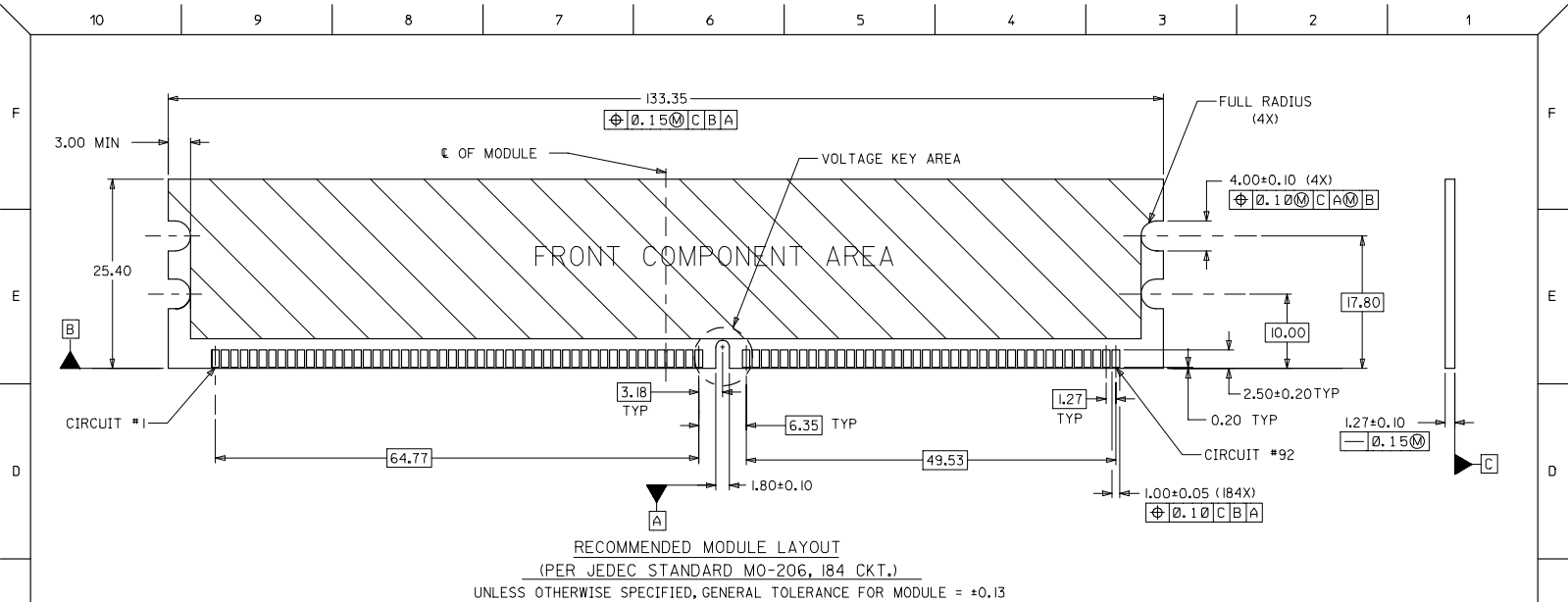


MINIMUM RECOMMENDED ROW TO ROW SPACING  
WHEN USING A 4.00 mm THICK  
MODULE (TYPICAL TSOP PACKAGING)

MINIMUM RECOMMENDED ROW TO ROW SPACING  
WHEN USING A 9.00 mm THICK  
MODULE (TYPICAL SOJ PACKAGING)

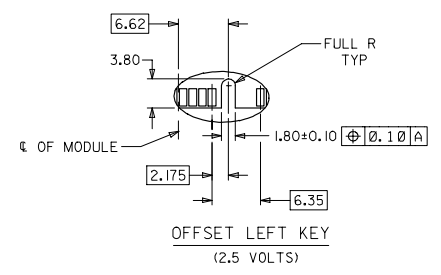
SECTION A-A

OBS. TIN/LEAD P/N EC NO. S2006-0734 DRAWN BY: DRW:HLONG CHKD: JHO APPR: GLEE 2006/02/27 2006/02/28 2006/03/01	QUALITY SYMBOLS ▽=0 ▽=0	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE NTS	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION	
		4 PLACES ± --- ± ---	DRAWN BY LPLIM	DATE 2000/01/10	TITLE DDR DIMM, 1.27MM PITCH 184 CKTS, 25 DEG.		MOLEX INCORPORATED		
		3 PLACES ± --- ± ---	CHECKED BY DSOH	DATE 2000/02/02	MATERIAL NO. SEE TABLE				
		2 PLACES ± 0.25 ± ---	APPROVED BY SKTOH	DATE 2000/02/02	SIZE A3		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION		
1 PLACE ± --- ± ---	ANGULAR ± 5 °		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS						



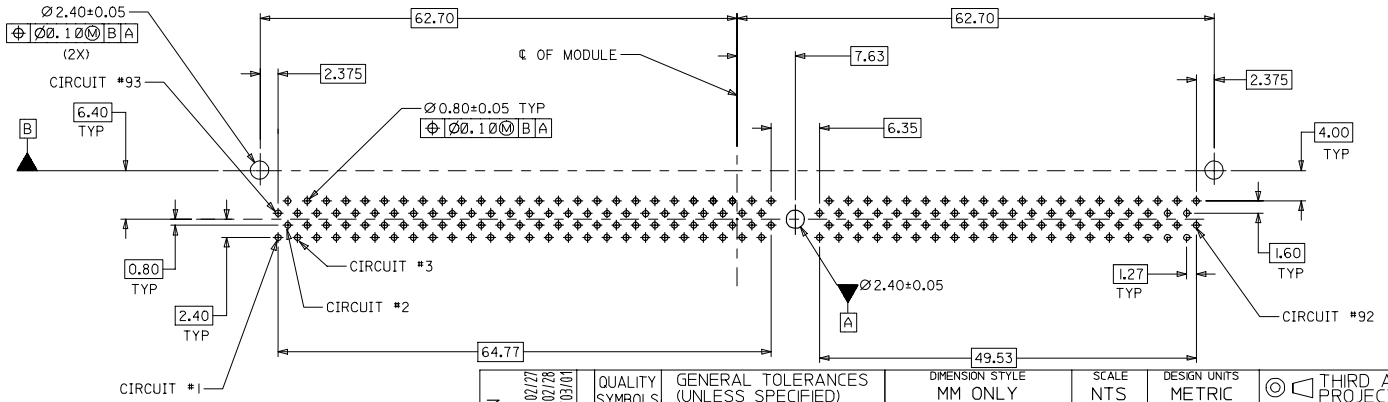
RECOMMENDED MODULE LAYOUT  
 (PER JEDEC STANDARD MO-206, 184 CKT.)  
 UNLESS OTHERWISE SPECIFIED, GENERAL TOLERANCE FOR MODULE = ±0.13

VOLTAGE KEY AREA



OBS. TIN/LEAD P/N EC NO. S2006-0734 DRAWN: LONG CHKD: HO APPR: GLEE REV C	DESCRIPTION 2006/02/27 2006/02/28 2006/03/01	QUALITY SYMBOLS ▽=0 ▽=0	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE NTS	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION		
			4 PLACES ± --- ± ---	3 PLACES ± --- ± ---	2 PLACES ± 0.25 ± ---	1 PLACE ± --- ± ---	ANGULAR ± 5 °	DRAWN BY LPL IM	DATE 2000/01/10	CHECKED BY DSOH	DATE 2000/02/02
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS			SEE TABLE		MATERIAL NO.		MOLEX INCORPORATED		DOCUMENT NO. SD-87623-001	SHEET NO. 3 OF 4	
THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION											

PART NUMBER	VOLTAGE KEY	CKT SIZE	TAIL LENGTH P±0.25	PEG LENGTH 0±0.25	FORK LENGTH R±0.25	RECOMMENDED PCB THICKNESS	FINISHES: CONTACT AREA	
87623-2001	LEFT (2.5V)	184	2.79	3.18	3.18	1.57	SELECTIVE GOLD 0.38µM/15µ" MIN. GOLD OVER 1.27µM/50µ" MIN. NICKEL	
87623-2011			3.18	4.83	3.94			
87623-2012			3.18	3.18	3.18			
87623-2013			3.81	4.83	4.42	2.84		
87623-2101			2.79	3.18	3.18	1.57		SELECTIVE GOLD 0.76µM/30µ" MIN. GOLD OVER 1.27µM/50µ" MIN. NICKEL
87623-2111			3.18	4.83	3.94			
87623-2113			3.81	4.83	4.42			
87623-2115			3.18	3.18	3.18			



RECOMMENDED  
P.C. BOARD HOLE PATTERN  
(CONNECTOR SIDE)

OBS: TIN/LEAD P/N EC NO. S2006-0734 DRAWING NO. 2006/02/27 CHKD: HHO APPR: GLEE 2006/03/01	QUALITY SYMBOLS ▽=0 ▽=0	GENERAL TOLERANCES (UNLESS SPECIFIED)	DIMENSION STYLE		SCALE	DESIGN UNITS	THIRD ANGLE PROJECTION
			MM ONLY	INCH			
			4 PLACES ± --- ± ---	LPL IM	DATE	DDR DIMM, 1.27MM PITCH 184 CKTS, 25 DEG.	
			3 PLACES ± --- ± ---	CHECKED BY	DATE	MOLEX INCORPORATED	
			2 PLACES ± 0.25 ± ---	DSOH	2000/02/02	MATERIAL NO. DOCUMENT NO. SD-87623-001	
			1 PLACE ± --- ± ---	APPROVED BY	DATE	SHEET NO. 4 OF 4	
			ANGULAR ± 5 °	SKTOH	2000/02/02	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION	
		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	SEE TABLE	SIZE	A3		